

	Type	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	389	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:32	
2	BRS	15	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:40	
3	BRS	27	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:41	
4	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:41	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	3	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:42	
6	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:43	
7	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) same prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:43	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
8	BRS	10	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) and prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:43	
9	BRS	8	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) and prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:45	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
10	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) and prevent\$3 with maintenance\$1 with manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:48	
11	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and prevent\$3 with maintenance\$1 same manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 11:53	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
12	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and prevent\$3 with maintenance\$1 same manag\$6 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) with tim\$3 with cost\$3 and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 12:15	
13	BRS	277	702/184.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 12:24	
14	BRS	477	700/95.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 12:16	
15	BRS	243	700/96.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 12:16	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
16	BRS	40	(semiconductor\$1 or wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and prevent\$3 with maintenance\$1 and parameter\$1 with process\$3 and (evaluat\$3 or validat\$3) and (analys\$3 or analyz\$3) and (stor\$3 or sav\$3 or record\$3) with (status or state\$1 or condition\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:18	
17	BRS	1178	702/176,177,178,184,187.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:06	
18	BRS	4501	700/12,14,17,19,108,121,174,175,176,178,180.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:27	
19	BRS	5382	700/12,14,17,19,108,117,121,174,175,176,178,180.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:27	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
20	BRS	29	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccl s.) and semiconductor\$1 with process\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:28	
21	BRS	0	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccl s.) and semiconductor\$1 with process\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:29	
22	BRS	0	semiconductor\$1 with process\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:29	

Type	Hits	Search Text	DBs	Time Stamp	Comments
23 BRS	5	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccl s.) and semiconductor\$1 with process\$3 and prevent\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:34	
24 BRS	0	(700/12,14,17,19,108,117,121,174,175,176,178,180.ccl s.) and semiconductor\$1 same process\$3 with parameter\$1 and prevent\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:34	
25 BRS	3	semiconductor\$1 same process\$3 with parameter\$1 and prevent\$3 with maintenance\$1 and (validat\$3 or evaluat\$3 or estimat\$3) with tim\$3 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:45	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
26	BRS	0	semiconductor\$1 with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:53	
27	BRS	15	semiconductor\$1 with equipment\$1 and semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:47	
28	BRS	5	semiconductor\$1 with equipment\$1 with semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:48	
29	BRS	1	semiconductor\$1 with equipment\$1 with semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and cost with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:50	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
30	BRS	7	semiconductor\$1 with equipment\$1 and semiconductor\$1 with product\$1 and prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and cost with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:50	
31	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:53	
32	BRS	6	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:54	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
33	BRS	2	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with product\$1 same prevent\$3 with maintenance\$1 and process\$3 with parameter\$1 and (estimat\$3 or validat\$3) evaluat\$3 or validat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:55	
34	BRS	11	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with equipment\$1 with maintenance\$1 and process\$3 with parameter\$1 and equipment\$1 with parameter\$1 and maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 12:59	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
35	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 with manag\$6 and (evaluat\$3 or estimat\$3 or validat\$3) with cost\$3 with tim\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:01	
36	BRS	1	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC\$1 or (integrated adj circuit\$1)) with maintenance\$1 and (evaluat\$3 or estimat\$3 or validat\$3) with cost\$3 with tim\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:02	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
37	BRS	0	(semiconductor\$1 or wafer\$1 or chip\$1 or die\$1 or IC or ICs or (integrated adj circuit\$1)) with maintenance\$1 and (evaluat\$3 or estimat\$3 or validat\$3) with cost\$3 with tim\$3 with maintenance\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:02	
38	BRS	1779	705/7,11.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:04	
39	BRS	3388	702/84,176,177,178,182,183,184,185,187.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:07	
40	BRS	34	(702/84,176,177,178,182,183,184,185,187.ccls.) and semiconductor\$1 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:08	
41	BRS	7	(702/84,176,177,178,182,183,184,185,187.ccls.) and semiconductor\$1 with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:08	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
42	BRS	0	(702/84,176,177,178,182,183,184,185,187.ccls.) and semiconductor\$1 with maintenance\$1 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
43	BRS	0	("702"/\$.ccls.) and semiconductor\$1 with maintenance\$1 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
44	BRS	0	("705"/\$.ccls.) and semiconductor\$1 with maintenance\$1 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
45	BRS	1	("705"/\$.ccls.) and semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
46	BRS	0	("700"/\$.ccls.) and semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:09	
47	BRS	1	("705"/\$.ccls.) and semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:23	
48	BRS	5	semiconductor\$1 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:12	
49	BRS	7	semiconductor\$1 same prevent\$3 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:16	

Type	Hits	Search Text	DBs	Time Stamp	Comments
50	BRS 10	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) same prevent\$3 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
51	BRS 11	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) same prevent\$3 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3 pr predict\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
52	BRS 68	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and prevent\$3 with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3 pr predict\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
53	BRS	3	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and prevent\$3 with maintenance\$1 with manag\$6 and (evaluat\$3 or validat\$3 or estimat\$3 pr predict\$3) with cost\$3 same tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:17	
54	BRS	1	"6327521".PN.	USPAT; USOCR	2005/05/23 13:19	
55	BRS	1	"6192287".PN.	USPAT; USOCR	2005/05/23 13:19	
56	BRS	1	"6090632".PN.	USPAT; USOCR	2005/05/23 13:20	
57	BRS	1	"5940300".PN.	USPAT; USOCR	2005/05/23 13:20	
58	BRS	1	"5910011".PN.	USPAT; USOCR	2005/05/23 13:21	
59	BRS	1	"4720806".PN.	USPAT; USOCR	2005/05/23 13:21	
60	BRS	1	"5327349".PN.	USPAT; USOCR	2005/05/23 13:21	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
61	BRS	4	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:24	
62	BRS	0	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with maintenance\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
63	BRS	0	("705"/\$.ccls.) and (wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with equipment\$1 and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:25	
64	BRS	0	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) with (workpiece\$1 or equipment\$1) and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
65	BRS	0	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	
66	BRS	1	(wafer\$1 or chip\$1 or die or dies or IC or ICs or (integrated adj circuit\$1) or semiconductor\$1) and (evaluat\$3 or validat\$3 or estimat\$3) with cost\$3 with tim\$3 same prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:26	
67	BRS	1	(piece\$1 or workpiece\$1) with (semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with equipment\$1 same prevent with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:33	
68	IS&R	2	("4860571").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:33	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
69	BRS	0	"6782302".uref.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 13:54	
70	BRS	0	prevent\$3 with maintenance\$1 with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM TDB	2005/05/23 13:57	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
71	BRS	0	prevent\$3 with maintenance\$1 same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:57	
72	BRS	17	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 13:59	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
73	BRS	2	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1 and cost\$3 with tim\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:00	
74	BRS	0	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) with equipment\$1 with product\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:01	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
75	BRS	0	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with product\$1 with (piece\$1 or workiece\$1) same equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:01	
76	BRS	55	prevent\$3 with maintenance\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) and equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:02	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
77	BRS	1	prevent\$3 with maintenance\$1 with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workiece\$1) and equipment\$1 with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:02	
78	BRS	7	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:07	
79	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:06	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
80	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 with prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:06	
81	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with (piece\$1 or workpiece\$1) with equipment\$1 same prevent\$3 with maintenance\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:06	
82	BRS	4	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with maintenance\$1 with manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
83	BRS	4	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with maintenance\$1 same manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	
84	BRS	55	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with maintenance\$1 and manag\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:09	
85	BRS	49	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1) or die or dies or chip\$1) with prevent\$3 with maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:10	
86	BRS	0	semicopnductor\$1 with prevent\$3 with maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:10	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
87	BRS	29	(semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:21	
88	BRS	7	(semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (evaluat\$3 or validat\$3 or estimat\$3 or predict\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:18	
89	BRS	1740	451/1,8.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:18	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
90	BRS	11	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:22	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
91	BRS	2	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 with manag\$6 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:23	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
92	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 with manag\$6 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:24	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
93	BRS	6	(semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3 with parameter\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:31	
94	BRS	343	438/5.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:26	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
95	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with equipment\$1 and process\$3 with parameter\$1 and user\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:31	
96	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and user\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:32	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
97	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:32	
98	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 same interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:32	
99	BRS	0	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and user\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:33	
100	BRS	7	(semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:22	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
101	BRS	0	(semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and computer\$1 with interface\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:34	
102	BRS	1	(semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and interface\$1 with (record\$3 or sav\$3 or stor\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:39	
103	BRS	0	(semiconductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with prevent\$3 with maintenance\$1 with cost\$3 and interface\$1 with database	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 14:39	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
104	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with cost\$3 with prevent\$3 with maintenanc\$1 with cost\$3 with (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:23	
105	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with prevent\$3 with maintenanc\$1 with cost\$3 same (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:24	
106	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with prevent\$3 with maintenanc\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:24	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
107	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same prevent\$3 with maintenanc\$1 with cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	
108	BRS	46	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same prevent\$3 with maintenanc\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	
109	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) same prevent\$3 with maintenanc\$1 same cost\$3 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:25	

	Type	Hits	Search Text	DBs	Time Stamp	Comments
110	BRS	0	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with cost\$3 same prevent\$3 with maintenanc\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:26	
111	BRS	2	(evaluat\$3 or validat\$3 or estimat\$3 or predict\$3) with qualit\$3 same prevent\$3 with maintenanc\$1 and (semicopnductor\$1 or wafer\$1 or IC or ICs or (integrated adj circuit\$1)) with process\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/23 15:26	